

**Notice of References Cited**

Application/Control No.

09/254,939

Applicant(s)/Patent Under  
Reexamination  
MIURA ET AL.

Examiner

Anh D. Mai

Art Unit

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**U.S. PATENT DOCUMENTS**

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Name        | Classification |     |
|---|---|--|-----------------|-------------|----------------|-----|
|   | A | US-5679599                                       | 10-1997         | Mehta       | 438            | 425 |
|   | B | US-5885883                                       | 03-1999         | Park et al. | 438            | 435 |
|   | C | US-  |                 |             |                |     |
|   | D | US-  |                 |             |                |     |
|   | E | US-  |                 |             |                |     |
|   | F | US-  |                 |             |                |     |
|   | G | US-  |                 |             |                |     |
|   | H | US-  |                 |             |                |     |
|   | I | US-  |                 |             |                |     |
|   | J | US-  |                 |             |                |     |
|   | K | US-  |                 |             |                |     |
|   | L | US-  |                 |             |                |     |
|   | M | US-  |                 |             |                |     |

**FOREIGN PATENT DOCUMENTS**

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Country | Name   | Classification |       |
|---|---|--|-----------------|---------|--------|----------------|-------|
|   | N | JP- 01-107554                                    | 04-1989         | Japan   | Kojiro | H01L           | 21/76 |
|   | O |  |                 |         |        |                |       |
|   | P |  |                 |         |        |                |       |
|   | Q |  |                 |         |        |                |       |
|   | R |  |                 |         |        |                |       |
|   | S |  |                 |         |        |                |       |
|   | T |  |                 |         |        |                |       |

**NON-PATENT DOCUMENTS**

| * |   | Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)  |
|---|---|--|
|   | U | H. S. Lee et al., An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI), 1996, IEEE, pp. 158-159. |
|   | V | C. P. Chang et al., A Highly Manufacturable Corner Rounding Solution for 0.18 micron Shallow Trench Isolation. 1997, IEEE, pp. 661-664       |
|   | W |  |
|   | X |  |

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.